Ultrathin Dielectric Materials to Be 3M Topic At IPC Embedded Passives Conference

A paper on the electrical performance and reliability advantages of using ultrathin (less than 25 microns) powerground cores for distributed embedded capacitance will be presented at the IPC International Conference on Embedded Passives by Joel Peiffer, engineering specialist, 3M Organic Materials Technology Center.

"Ultra-Thin, Loaded Epoxy Materials for Use as Embedded Capacitor Layers" will be presented Wednesday, June 11. Test results from leading OEM's, printed circuit fabricators and industry consortia will be reviewed, including comparisons of ultrathin embedded capacitor materials to existing commercial embedded capacitor materials and discrete surface-mounted (SMT) components. Additionally, data will be presented which will give board designers an idea of how much discrete capacitance can be removed by the use of ultrathin, high-capacitance, power-ground cores in printed circuit boards.

"Ultra-Thin, Loaded Epoxy Materials for Use as Embedded Capacitor Layers"

3M is an active member of IPC-Association Connecting Electronics Industries and the Advanced Embedded Passives Technology (AEPT) Consortium.

For more information on 3M brand embedded capacitor material, contact Bill Balliette, new product development manager, 3M Microinterconnect Systems Division, (512) 984-7324, or visit 3M's exhibit at the IPC conference.

3M Microinterconnect Systems provides custom, high-performance flexible circuits for today's demanding electronics applications, including ink-jet printers, hard disk drives, optoelectronics, liquid crystal displays, medical, bio-analytical, IC packaging and other fine-pitch interconnect applications. 3M's technology, materials and process expertise enable its offering of circuits with one- and two-metal layer construction, and liquid crystal polymer or polyimide substrates. The division also supplies high-density multilayer interconnect solutions for electronics and photonics packaging. These high-density laminated chip packages provide breakthrough density and outstanding electrical performance optimized for ASICs in high bandwidth and networking applications.

About 3M

3M is a \$16 billion diversified technology company with leading positions in consumer and office; display and graphics; electronics and telecommunications; health care; industrial; safety, security and protection services; transportation and other businesses. Headquartered in St. Paul, Minnesota, the company has operations in more than 60 countries and serves customers in nearly 200 countries. 3M is one of the 30 stocks that make up the Dow Jones Industrial Average and also is a component of the Standard & Poor's 500 Index. For more information about 3M, go to <u>www.3M.com.</u>

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